



SOT1863-1

SO8, plastic, small outline package; 8 terminals; 2.54 mm pitch; 10.67 mm x 10.67 mm x 12.96 mm body

5 January 2018

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SO8
Package type industry code	SO8
Package style descriptive code	SO (small outline)
Package body material type	P (plastic)
JEDEC package outline code	E-PDIP-F8
Mounting method type	S (surface mount)
Issue date	24-10-2017
Manufacturer package code	98ASB17759C

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	-	-	10.67	-	mm
E	package width	-	-	10.67	-	mm
A ₂	package height	-	-	12.96	-	mm
e	nominal pitch	-	-	2.54	-	mm
n ₂	actual quantity of termination	-	-	8	-	A/A



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2. Package outline

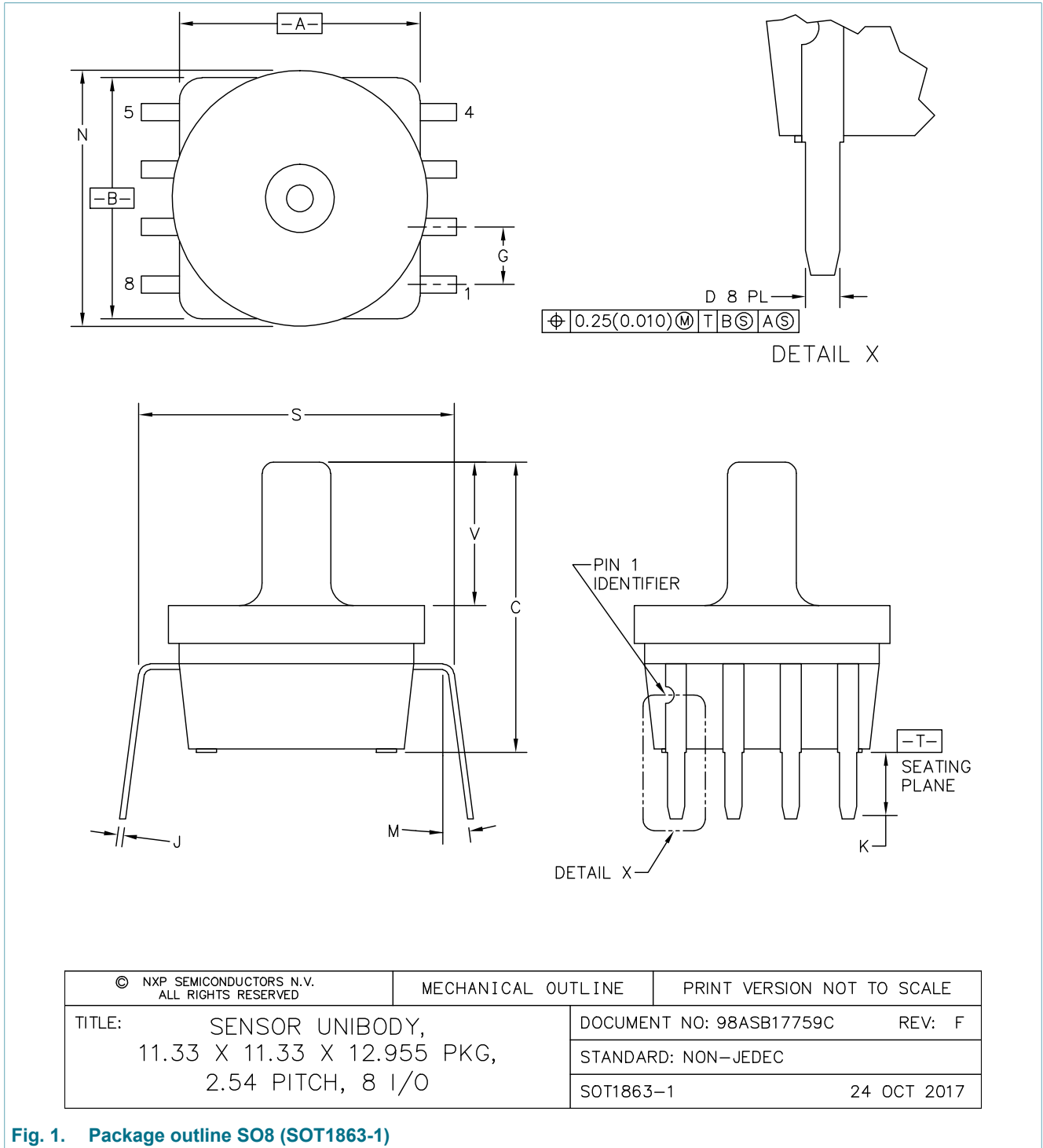


Fig. 1. Package outline SO8 (SOT1863-1)

SO8, plastic, small outline package; 8 terminals; 2.54 mm pitch; 10.67 mm x 10.67 mm x 12.96 mm body

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION 'A' AND 'B' DO NOT INCLUDE MOLD PROTUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006).
5. ALL VERTICAL SURFACES 5° TYPICAL DRAFT.
6. DIMENSION 'S' TO CENTER OF LEAD WHEN FORMED PARALLEL.
7. 482C-01 AND -02 OBSOLETE. NEW STANDARD 482C-03.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	10.54	10.79	0.415	0.425
B	10.54	10.79	0.415	0.425
C	12.70	13.21	0.500	0.520
D	0.66	0.864	0.026	0.034
G	2.54	BSC	0.100	BSC
J	0.23	0.28	0.009	0.011
K	2.54	3.05	0.100	0.120
M	0°	15°	0°	15°
N	11.28	11.38	0.444	0.448
S	13.72	14.22	0.540	0.560
V	6.22	6.48	0.245	0.255
W	2.92	3.17	0.115	0.125

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TITLE: SENSOR UNIBODY, 11.33 X 11.33 X 12.955 PKG, 2.54 PITCH, 8 I/O			DOCUMENT NO: 98ASB17759C		REV: F		
			STANDARD: NON-JEDEC				
			SOT1863-1		24 OCT 2017		

Fig. 2. Package outline note SO8 (SOT1863-1)

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3. Legal information

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